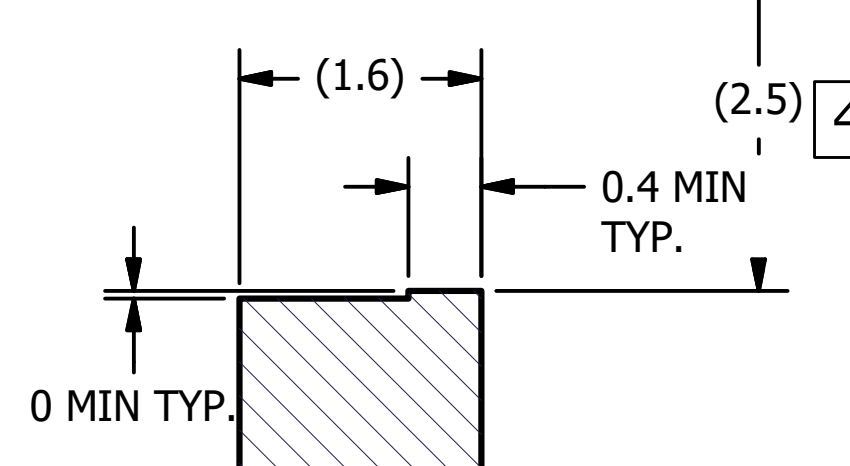
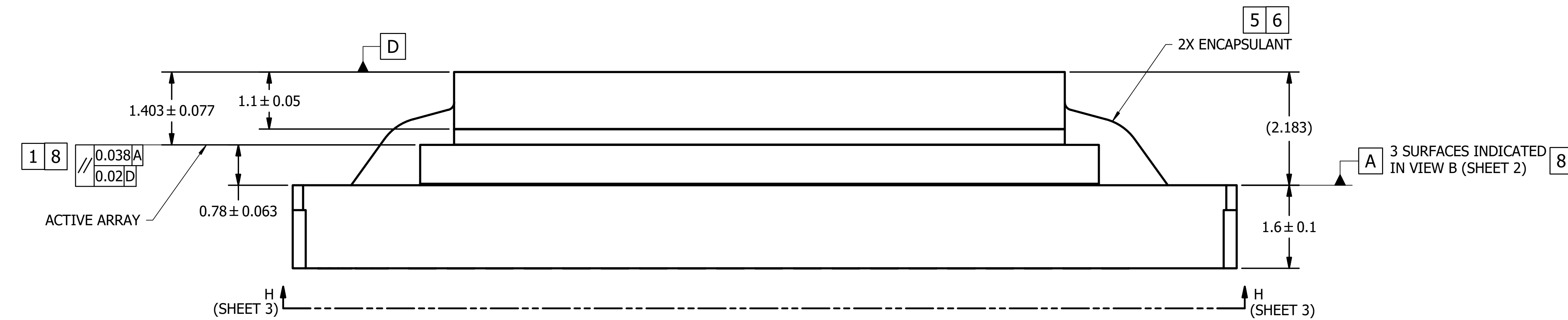
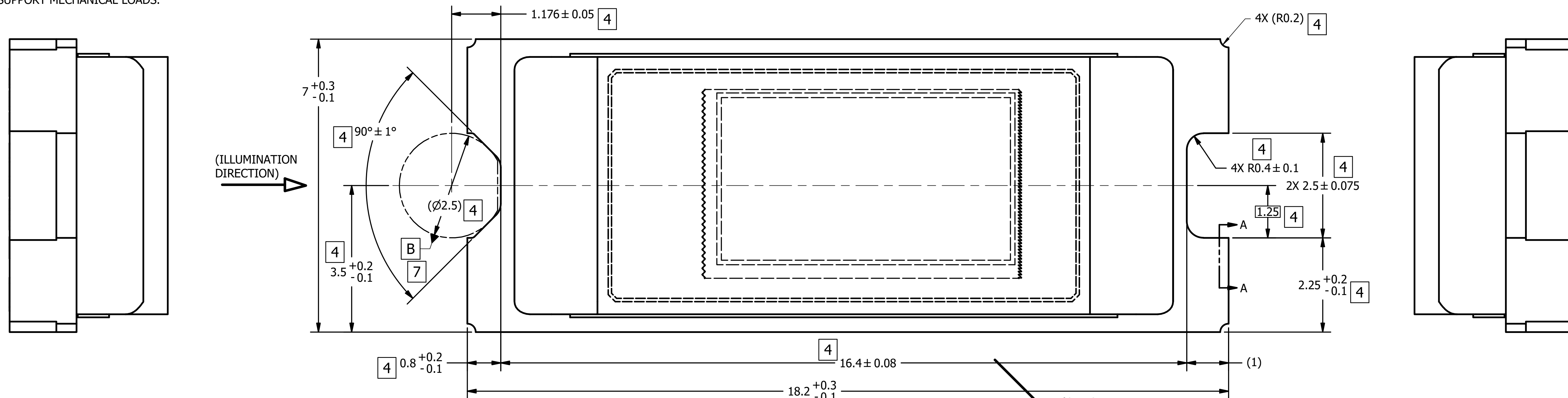


NOTES UNLESS OTHERWISE SPECIFIED:

- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
- 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
- 4 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
- 5 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW C (SHEET 2). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
- 6 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
- 7 DATUM B IS DEFINED BY A DIA. 2.5 PIN, WITH A FLAT ON THE SIDE FACING TOWARD THE CENTER OF THE ACTIVE ARRAY, AS SHOWN IN VIEW B (SHEET 2).
- 8 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.

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REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2133835: INITIAL RELEASE	6/6/2013	BMH
B	ECO 2134093: CORRECT WINDOW THK TOL, ZONE B6	6/17/2013	BMH
C	ECO 2186947: ADD APERTURE SLOTS PICTORIALY	4/8/2020	PPC

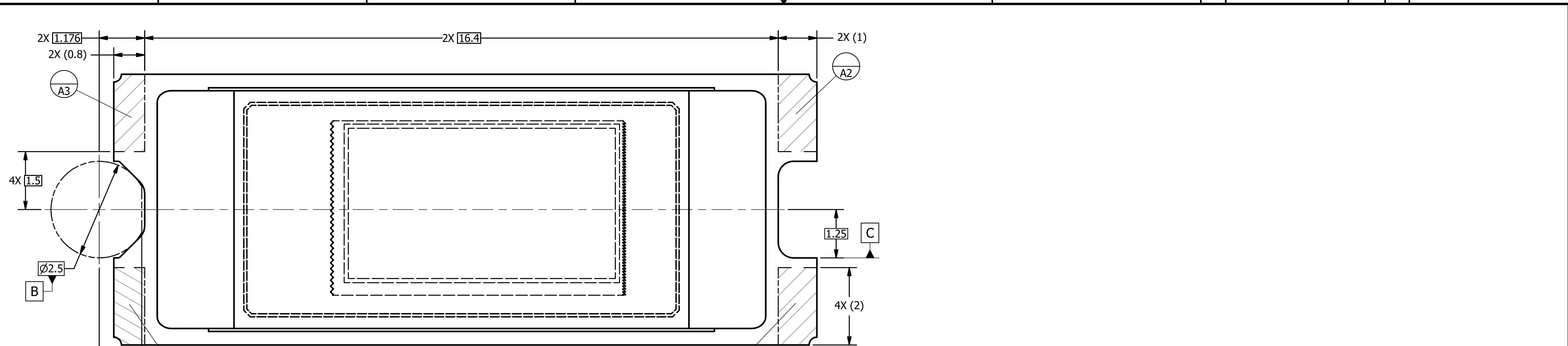


SECTION A-A
NOTCH OFFSETS

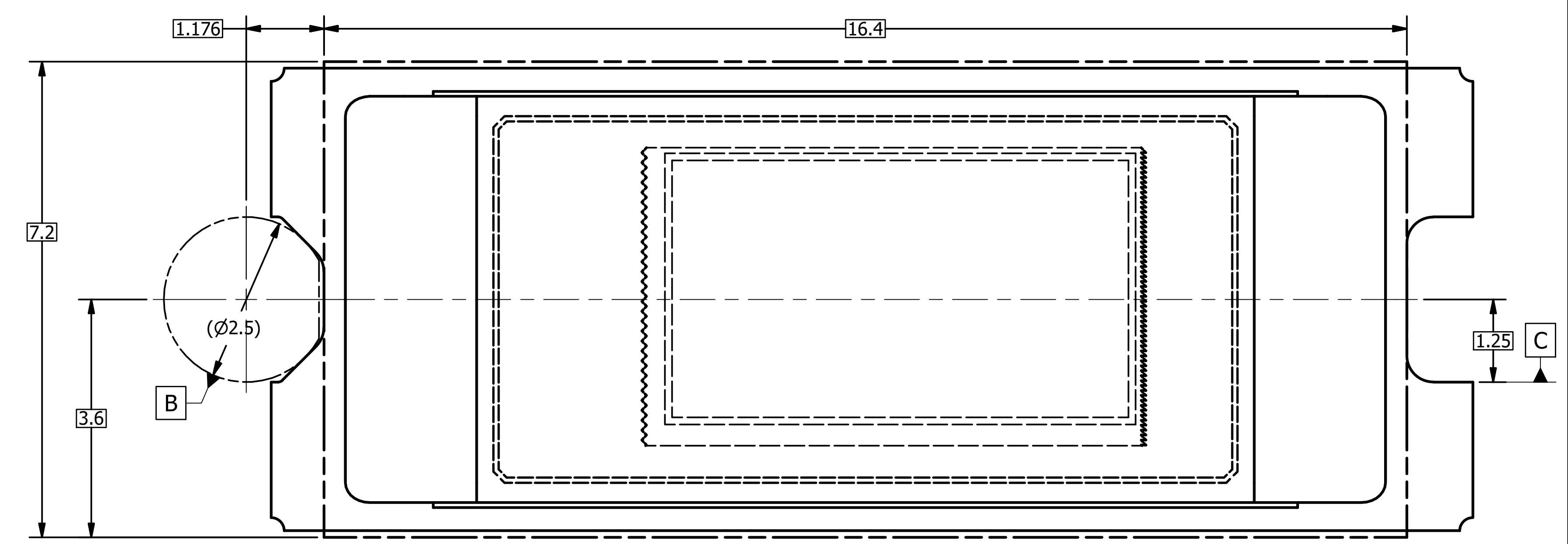
UNLESS OTHERWISE SPECIFIED	
• DIMENSIONS ARE IN MILLIMETERS	
• TOLERANCES:	
ANGLES ± 1°	
2 PLACE DECIMALS ± 0.25	
1 PLACE DECIMALS ± 0.50	
• DIMENSIONAL LIMITS APPLY BEFORE PROCESSING	
• INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994	
• REMOVE ALL BURRS AND SHARP EDGES	
• PARENTHETICAL INFORMATION FOR REFERENCE ONLY	
THIRD ANGLE PROJECTION	0314DA
NEXT ASSY	USED ON
APPLICATION	

DRAWN	DATE
B. HASKETT	6/6/2013
ENGINEER	
B. HASKETT	6/6/2013
QA/CE	
P. KONRAD	6/7/2013
CM	
S. SUSI	6/6/2013
S. CROFF	6/10/2013
APPROVED	
R. LONG	6/6/2013

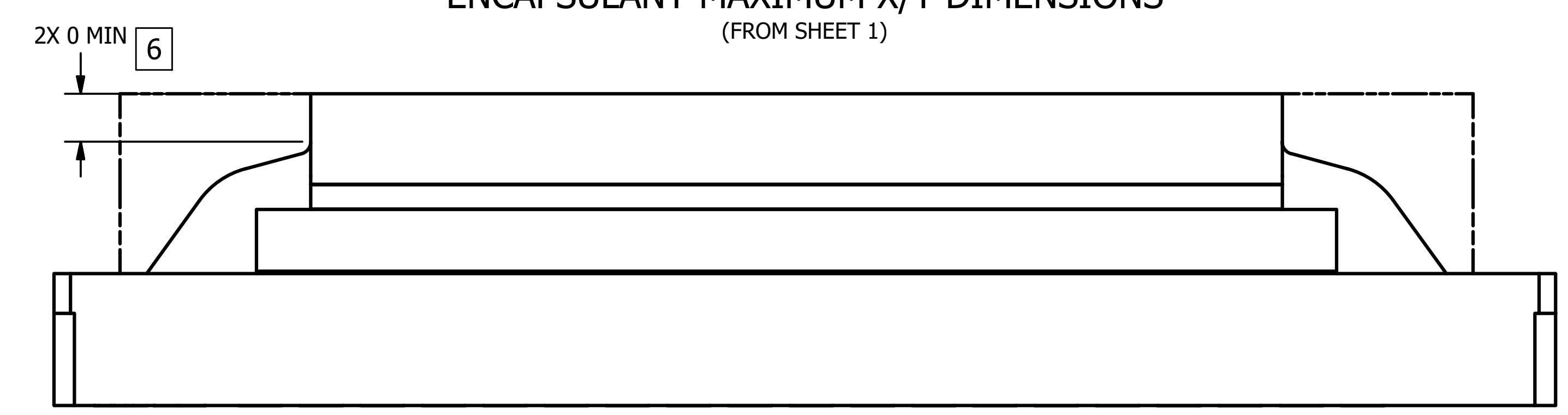
TITLE	
ICD, MECHANICAL, DMD, .3 720p SERIES 245 (FQK PACKAGE)	
SIZE	DWG NO.
D	2512014
SCALE	SHEET 1 OF 3
20:1	



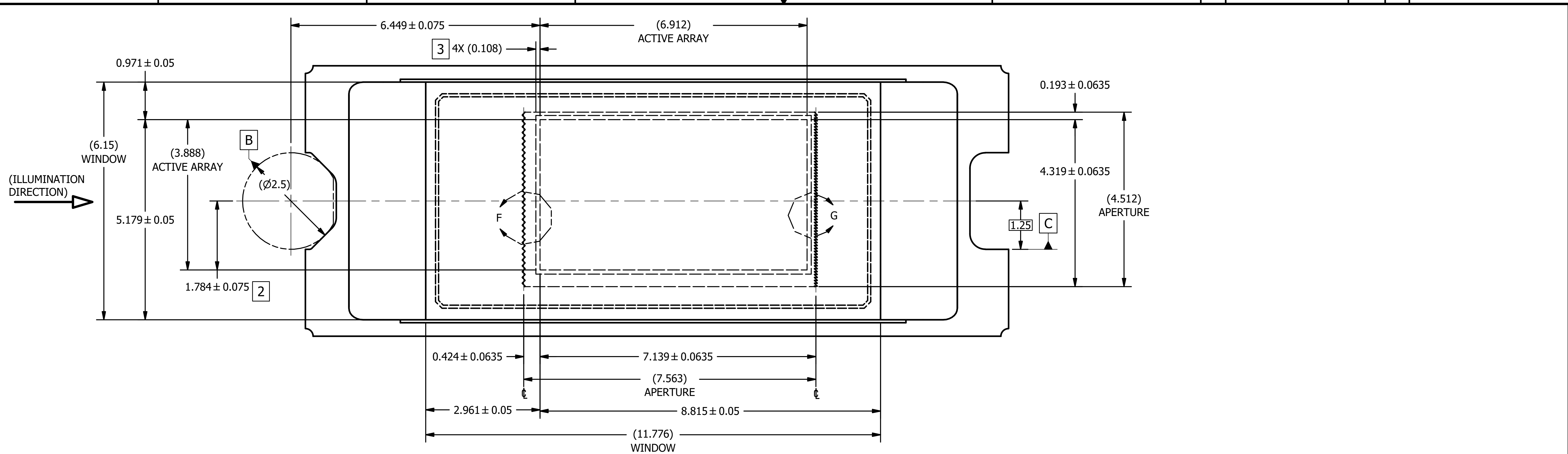
VIEW B
DATUMS A, B, C, AND E
(FROM SHEET 1)



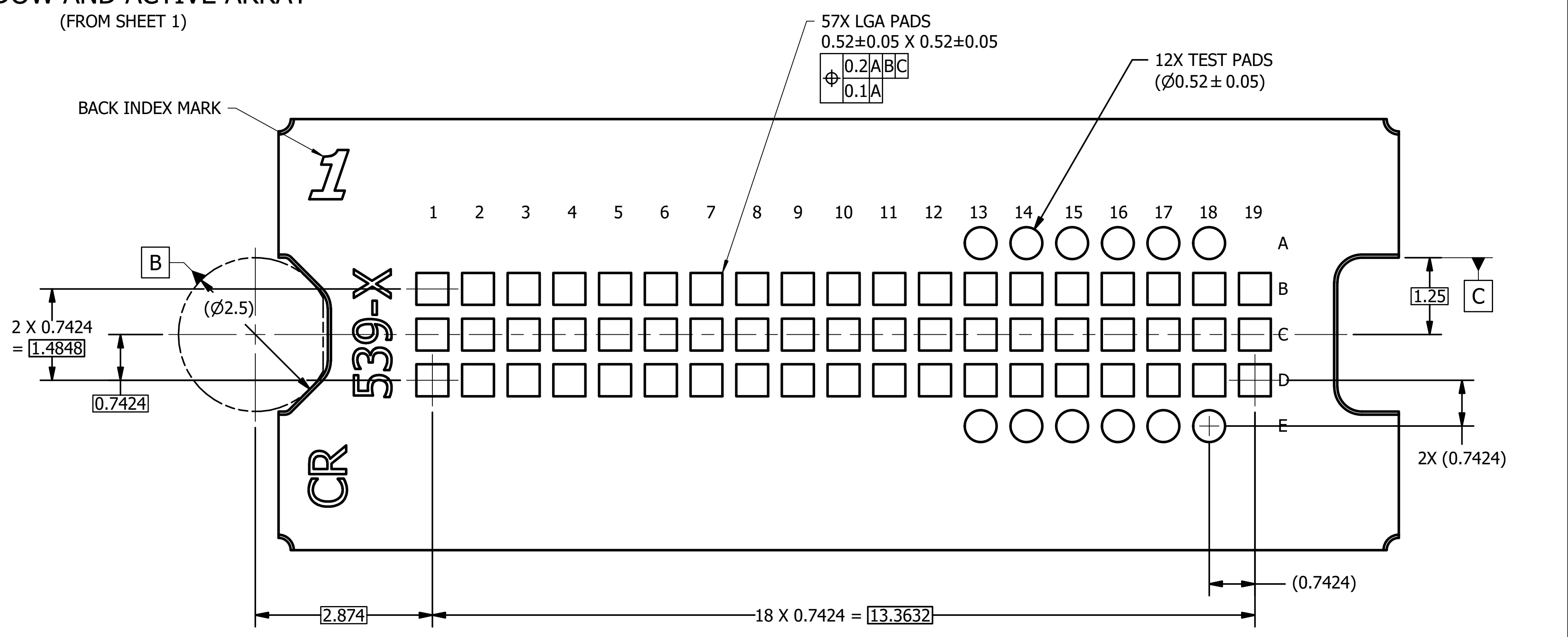
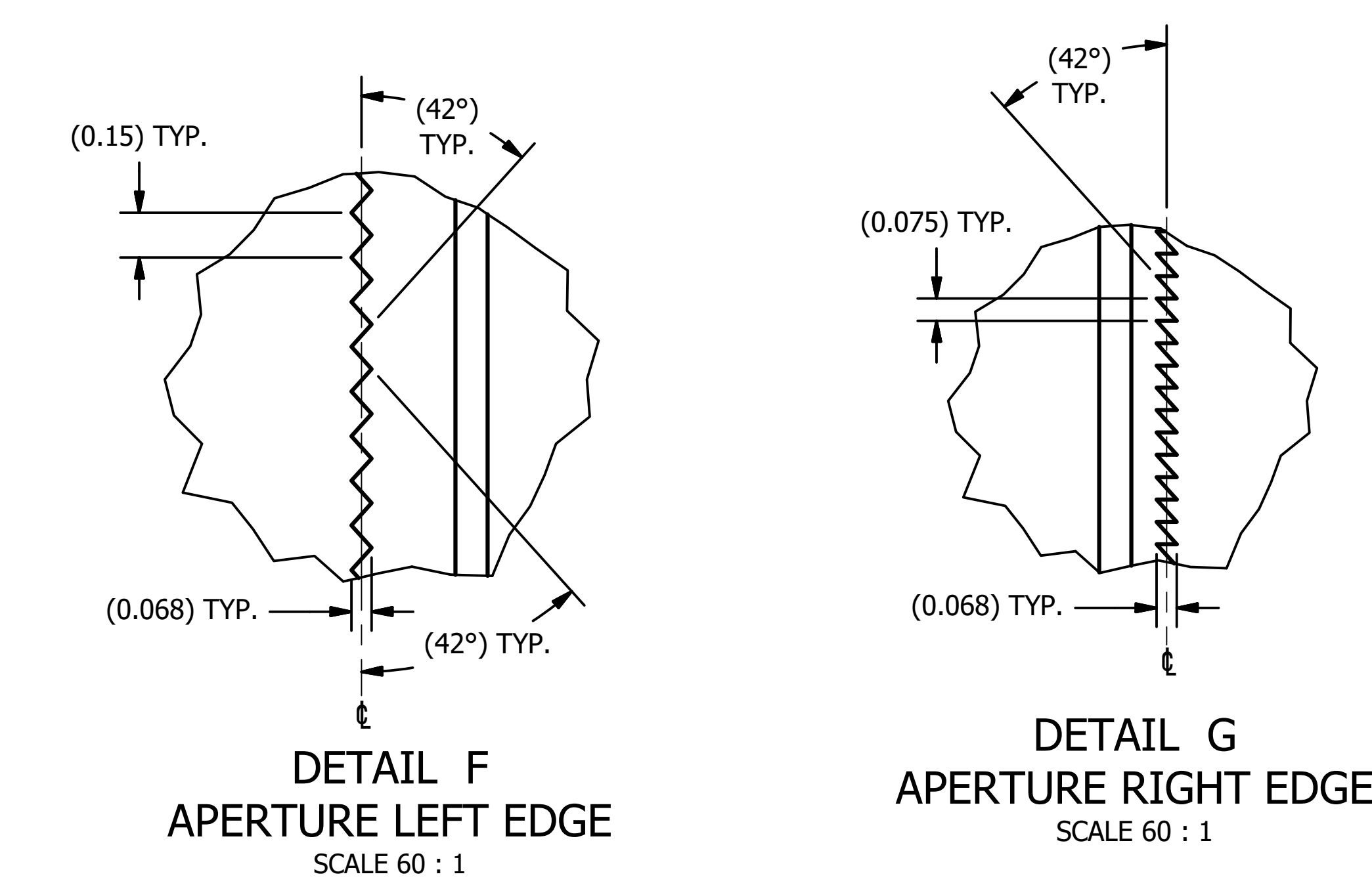
VIEW C 5
ENCAPSULANT MAXIMUM X/Y DIMENSIONS
(FROM SHEET 1)



VIEW D
ENCAPSULANT MAXIMUM HEIGHT



VIEW E
WINDOW AND ACTIVE ARRAY
(FROM SHEET 1)



VIEW H-H
BACK SIDE METALLIZATION
(FROM SHEET 1)

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